

2/9/1

DIALOG(R) File 347:JAPIO

(c) 1998 JPO & JAPIO. All rts. reserv.

04425380

MOUNTING STRUCTURE FOR BARE CHIP

PUB. NO.: 06-069280 [JP 6069280 A]
PUBLISHED: March 11, 1994 (19940311)
INVENTOR(s): KUSAYA TOSHIHIRO
KADOI KAZUHISA
APPLICANT(s): FUJITSU LTD [000522] (A Japanese Company or Corporation), JP
(Japan)
APPL. NO.: 04-218109 [JP 92218109]
FILED: August 18, 1992 (19920818)
INTL CLASS: (S) H01L-021/60; H01L-021/60
JAPIO CLASS: 42.2 (ELECTRONICS -- Solid State Components)
JOURNAL: Section: E, Section No. 1561, Vol. 18, No. 311, Pg. 93, June
14, 1994 (19940614)

ABSTRACT

PURPOSE: To facilitate removal of a bare chip by curing an insulating layer for fixing the chip to a predetermined surface of a board by heating, and further forming it of a synthetic resin material to be softened by heating it to a temperature higher than the predetermined temperature.

CONSTITUTION: The mounting structure for a bare chip comprises a board 8 having pads 3 to be connected to connecting parts 2 through a leader pattern 9 and formed at predetermined surface 1A of an insulating member 1. a bare chip 4 having electrodes 5, and bumps 7 for connecting the pads 3 to the electrodes 5. The chip 4 is fixed to the surface 1A through an insulating layer 6, and the electrodes 5 are so connected as to have conduction with the parts 2. In such a mounting structure of the chip 4, the layer 6 is so cured by heating it to a predetermined temperature T1 as to remove the chip 4 from the board 8 as required and formed of synthetic resin to be softened by heating to a temperature T2 higher than the temperature T1.